Green

40V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET
PowerDI5060-8

Product Summary

| BV_{DSS}	$R_{DS(ON)}$ Max	I_D Max T_C = +25°C
40V	8.8mΩ @ V_{GS} = 10V	64.8A
	13mΩ @ V_{GS} = 5V	53.3A

Features

- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching, Test in Production – Ensures More Reliable And Robust End Application
- Low $R_{DS(ON)}$ – Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**
  https://www.diodes.com/quality/product-definitions/
- **An automotive-compliant part is available under separate datasheet (DMTH4008LPSQ)**

Description and Applications

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- BLDC motors
- DC-DC converters
- Load switches

Mechanical Data

- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⓔ3
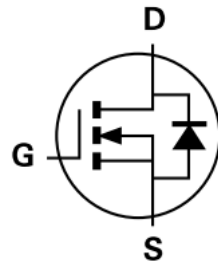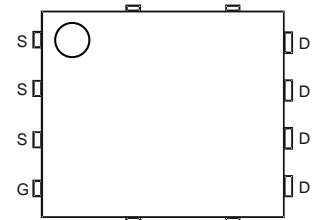- Weight: 0.097 grams (Approximate)

Site 1:
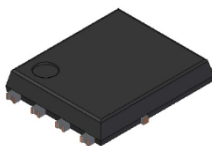
PowerDI5060-8

Top View

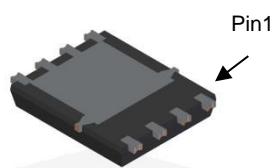Bottom View

Pin1
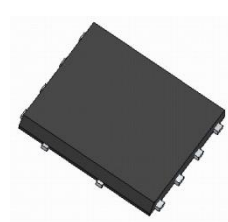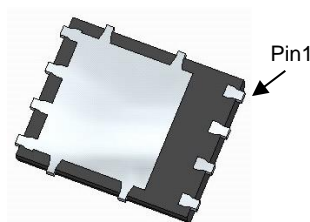
Internal Schematic

Top View
Pin Configuration

Site 2:

PowerDI5060-8/SWP (Type UX)

Top View

Bottom View

Pin1
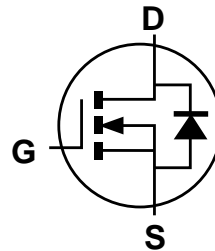
Internal Schematic
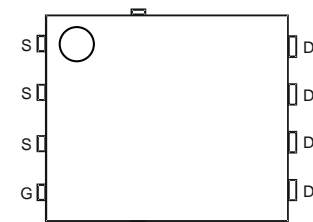
Top View
Pin Configuration

Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMTH4008LPS-13	PowerDI5060-8	2,500	Tape & Reel
DMTH4008LPS-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel

Note: 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information
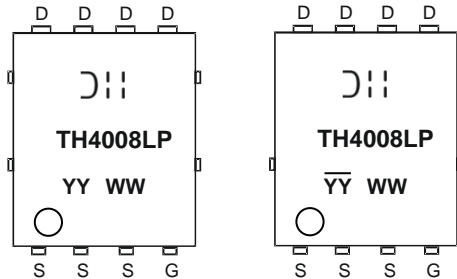
⊃¦¦ = Manufacturer's Marking
TH4008LP = Product Type Marking Code
YYWW = Date Code Marking
YY or $\overline{YY}$ = Last Two Digits of Year (ex: 23 = 2023)
WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	40	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current, V_{GS} = 10V (Note 5)	T_A = +25°C	I_D	14.4	A
	T_A = +100°C		10.2	
Continuous Drain Current, V_{GS} = 10V (Note 6)	T_C = +25°C	I_D	64.8	A
	T_C = +100°C		45.8	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I_{DM}	110	A
Maximum Continuous Body Diode Forward Current (Note 6)		I_S	55.5	A
Avalanche Current, L = 0.1mH		I_{AS}	22.7	A
Avalanche Energy, L = 0.1mH		E_{AS}	25.7	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	2.99	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	50.4	°C/W
Total Power Dissipation (Note 6)	T_C = +25°C	P_D	55.5	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	2.7	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +175	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
6. Thermal resistance from junction to soldering point (on the exposed drain pad).

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	40	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 32V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	1.6	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	7.3	8.8	mΩ	V_{GS} = 10V, I_D = 10A
		—	10	13		V_{GS} = 5V, I_D = 10A
Diode Forward Voltage	V_{SD}	—	0.8	1.0	V	V_{GS} = 0V, I_S = 10A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1,088	—	pF	V_{DS} = 20V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	322	—		
Reverse Transfer Capacitance	C_{rss}	—	27	—		
Gate Resistance	R_g	—	2.6	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	7.4	—	nC	V_{DS} = 20V, I_D = 10A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	15.3	—		
Gate-Source Charge	Q_{gs}	—	2.4	—		
Gate-Drain Charge	Q_{gd}	—	3.4	—		
Turn-On Delay Time	$t_{D(ON)}$	—	4.3	—	ns	V_{DD} = 20V, V_{GS} = 10V, I_D = 10A, R_G = 6Ω
Turn-On Rise Time	t_R	—	7.5	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	16.7	—		
Turn-Off Fall Time	t_F	—	5.8	—		
Body Diode Reverse Recovery Time	t_{RR}	—	20.2	—	ns	I_F = 10A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	8.9	—	nC	

Notes: 7. Short duration pulse test used to minimize self-heating effect.
         8. Guaranteed by design. Not subject to product testing.

DMTH4008LPS
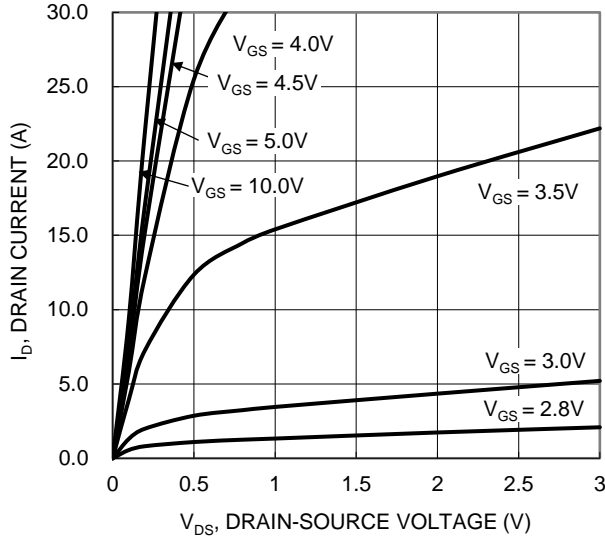Document number: DS40425 Rev. 3 - 2

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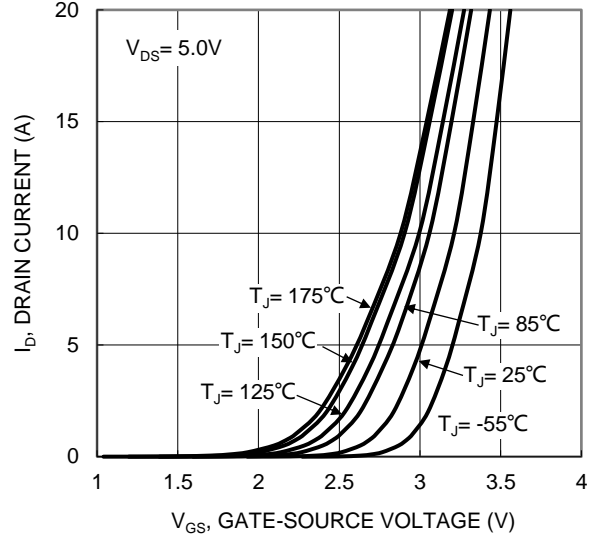Figure 1.Typical Output Characteristic
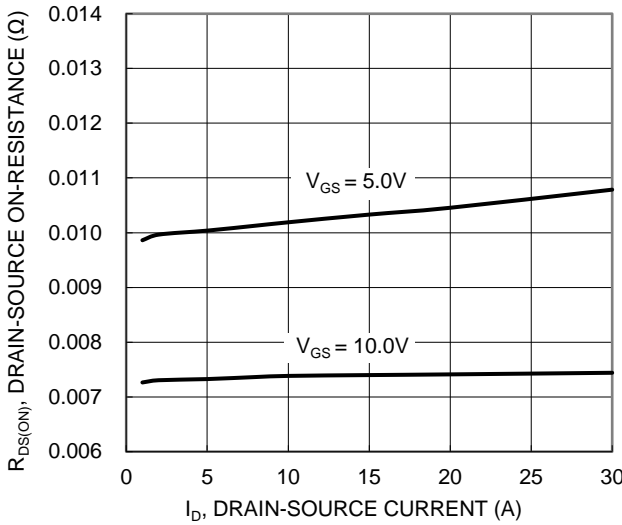

Figure 2. Typical Transfer Characteristic

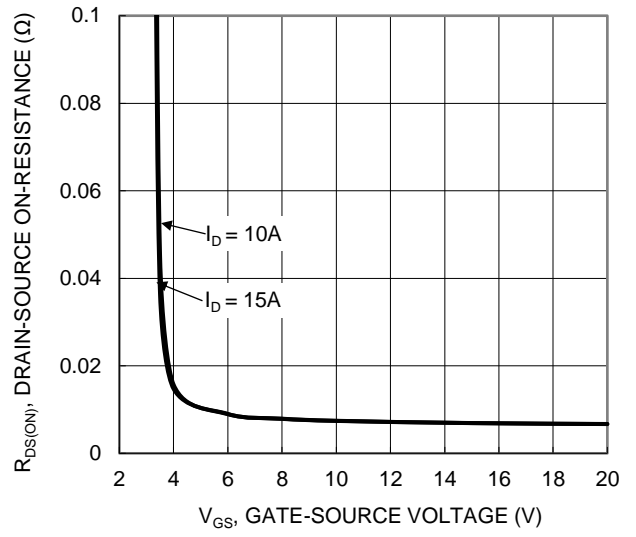Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

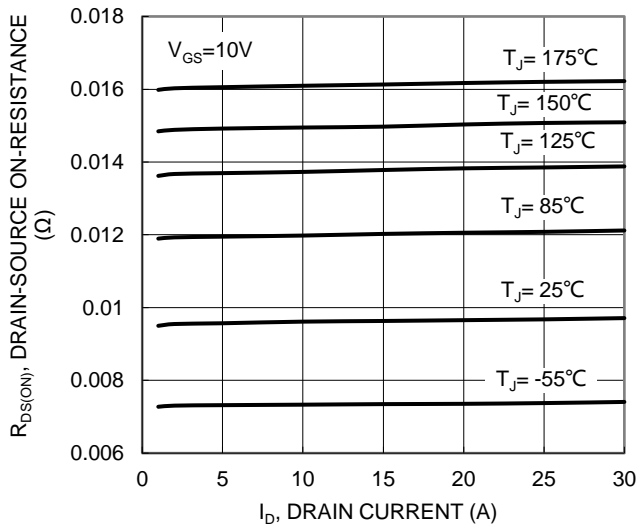Figure 4. Typical Transfer Characteristic

Figure 5. Typical On-Resistance vs. Drain Current and Temperature
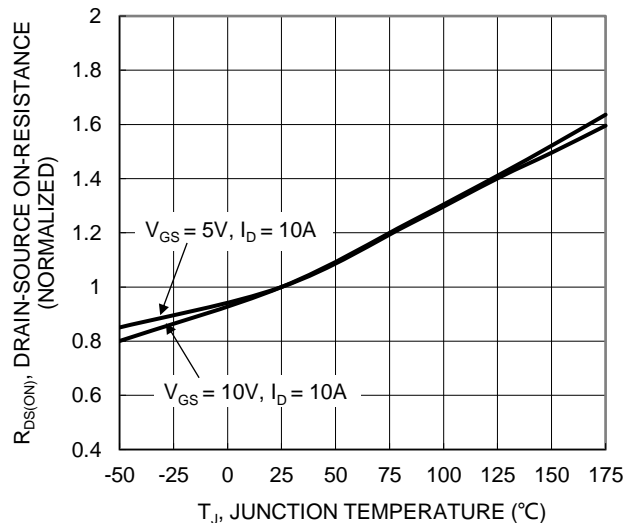
Figure 6. On-Resistance Variation with Temperature

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Figure 7. On-Resistance Variation with Temperature

Figure 8. Gate Threshold Variation vs. JunctionTemperature

Figure 9. Diode Forward Voltage vs. Current

Figure 10. Typical Junction Capacitance

Figure 11. Gate Charge

Figure 12. SOA, Safe Operation Area
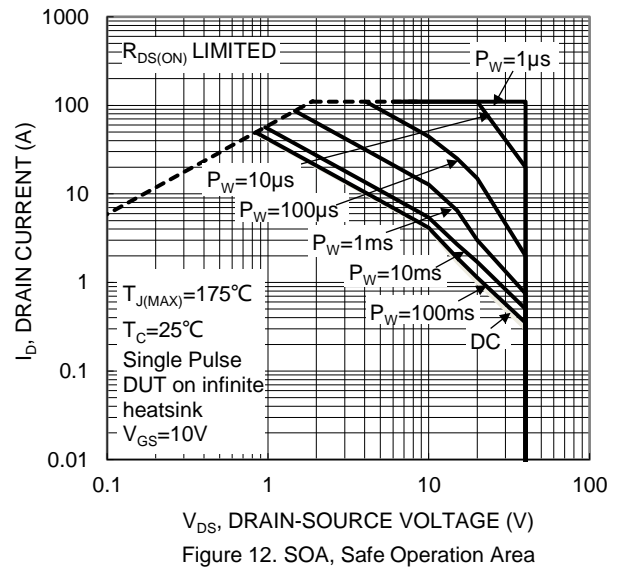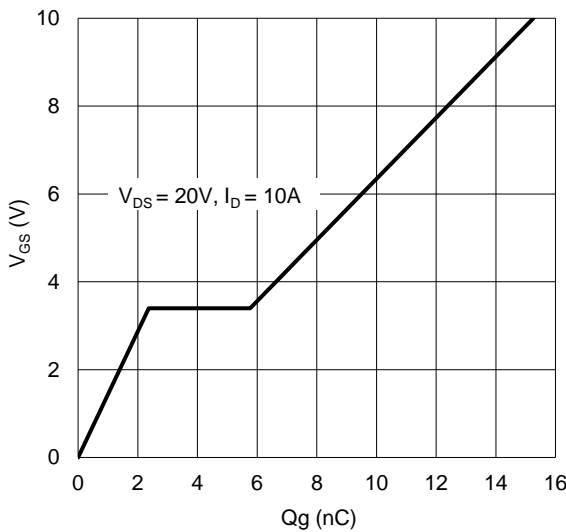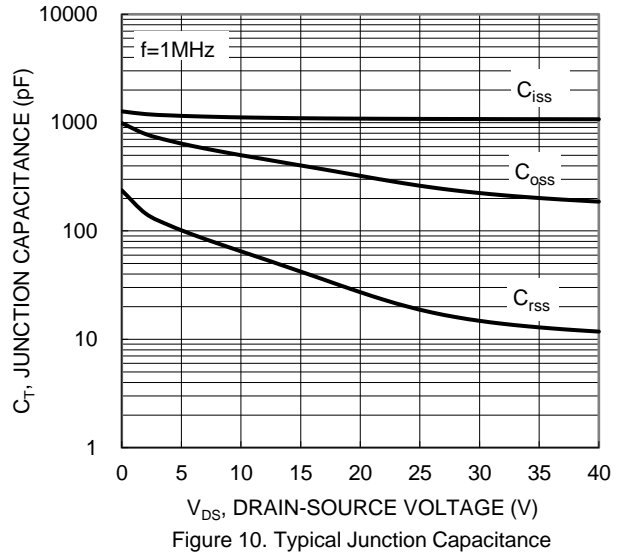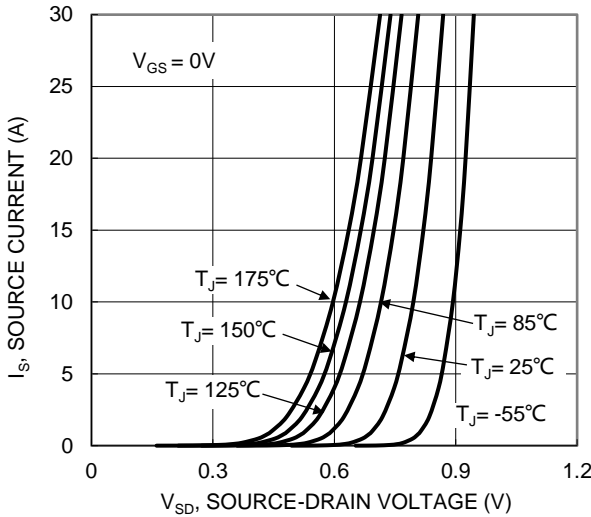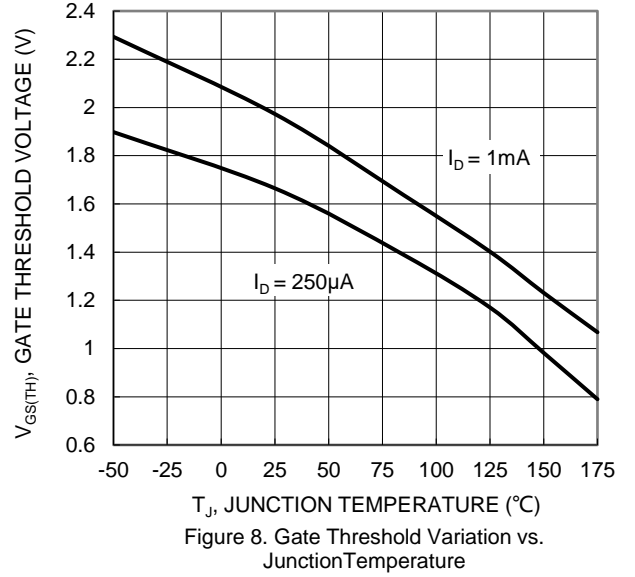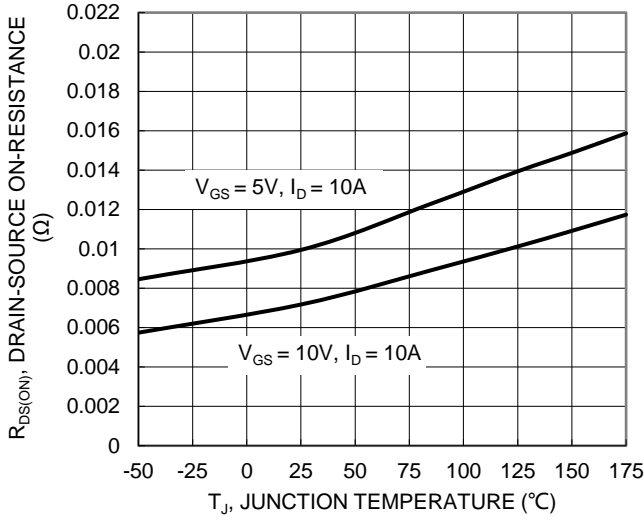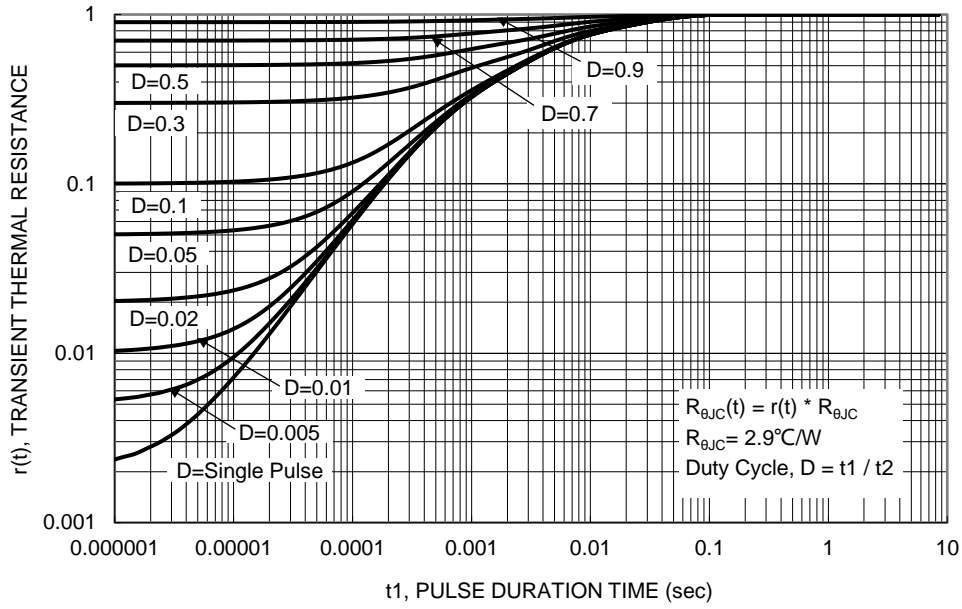
Figure 13. Transient Thermal Resistance

Within the figure:
- r(t), TRANSIENT THERMAL RESISTANCE (y-axis)
- t1, PULSE DURATION TIME (sec) (x-axis)
- D=0.9
- D=0.7
- D=0.5
- D=0.3
- D=0.1
- D=0.05
- D=0.02
- D=0.01
- D=0.005
- D=Single Pulse
- $R_{\theta JC}(t) = r(t) * R_{\theta JC}$
- $R_{\theta JC} = 2.9°C/W$
- Duty Cycle, D = t1 / t2

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Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

Site 1:
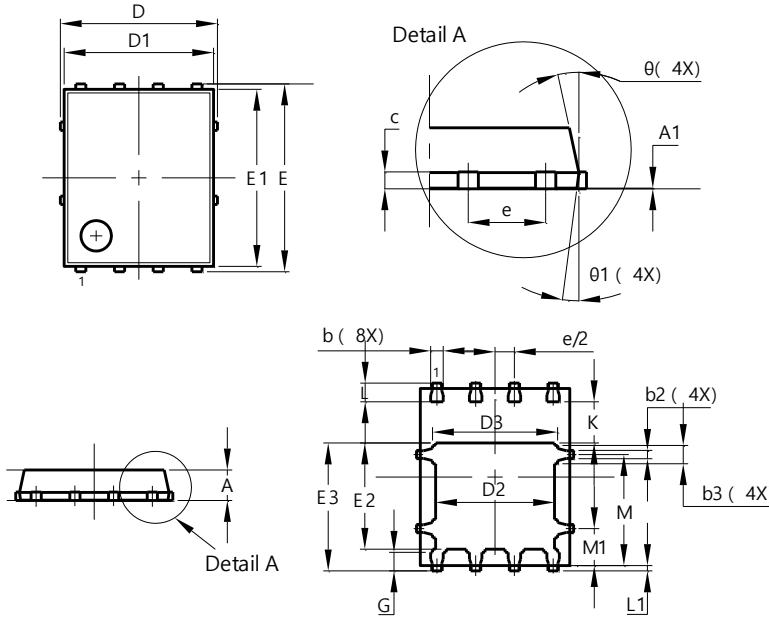
PowerDI5060-8

PowerDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	–
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	–	–
L	0.51	0.71	0.61
L1	0.100	0.200	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
Θ	10°	12°	11°
Θ1	6°	8°	7°
All Dimensions in mm			

Site 2:

PowerDI5060-8/SWP (Type UX)
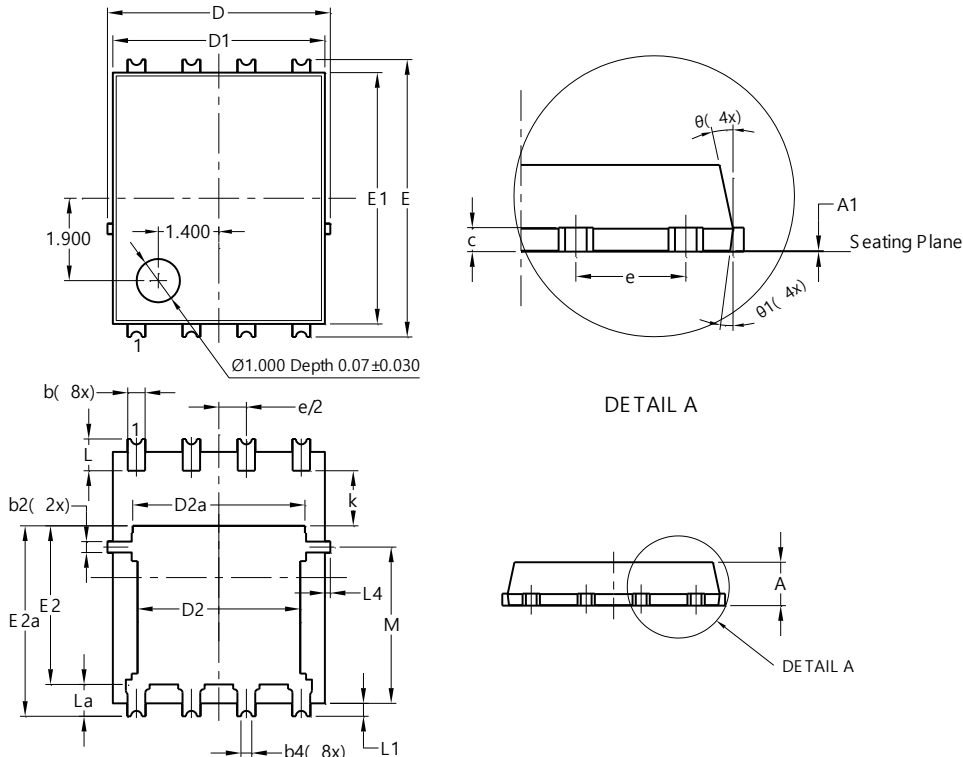
PowerDI5060-8/SWP (Type UX)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.56	3.96	3.76
D2a	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
L1a	0.050REF		
L4	0.025	0.225	0.125
M	3.205	4.005	3.605
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

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Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

Site 1:
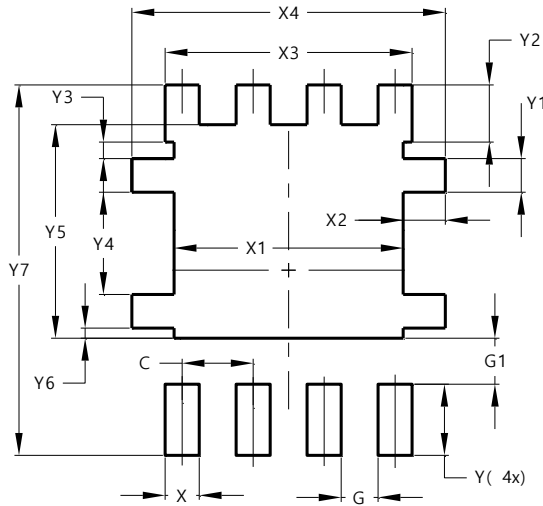
PowerDI5060-8

Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

PowerDI5060-8/SWP (Type UX)
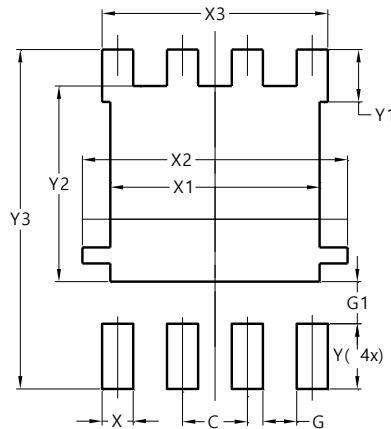
Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	5.190
X3	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

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